jwq40260 发行版本 *0.0*

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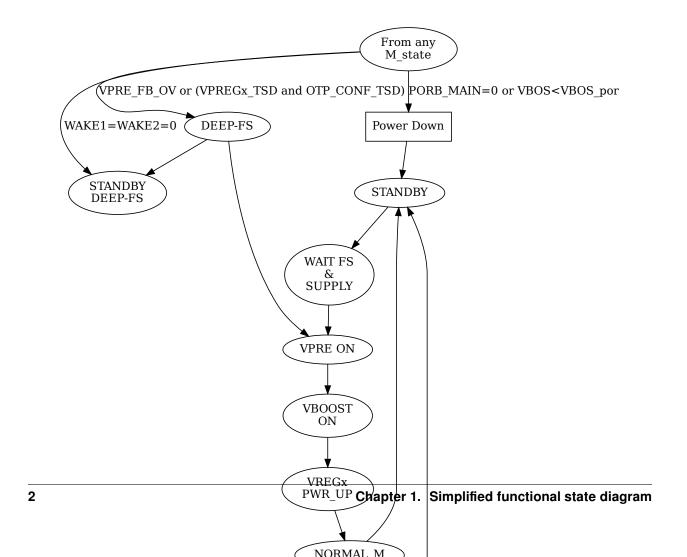
2023年09月25日

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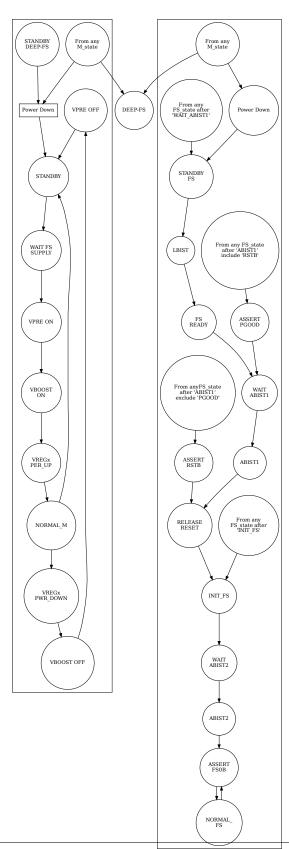
Simplified functional state diagram

1.1 graphviz



1.1. graphviz 3

1.2 graphviz1

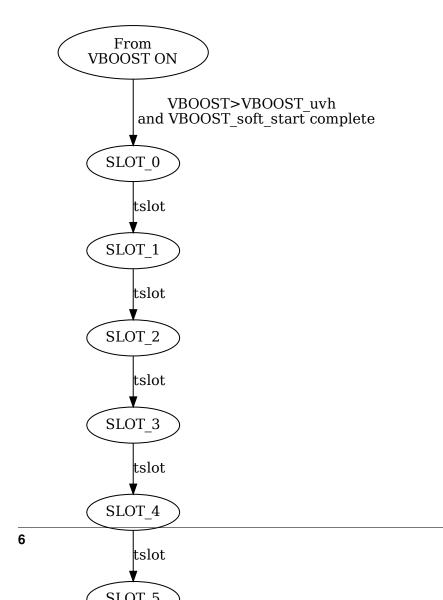


Chapter 1. Simplified functional state diagram

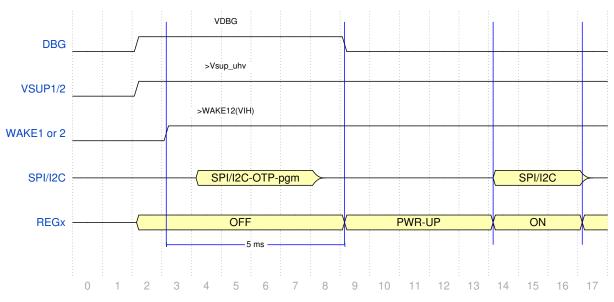
$\mathsf{CHAPTER}\, 2$

Power sequencing

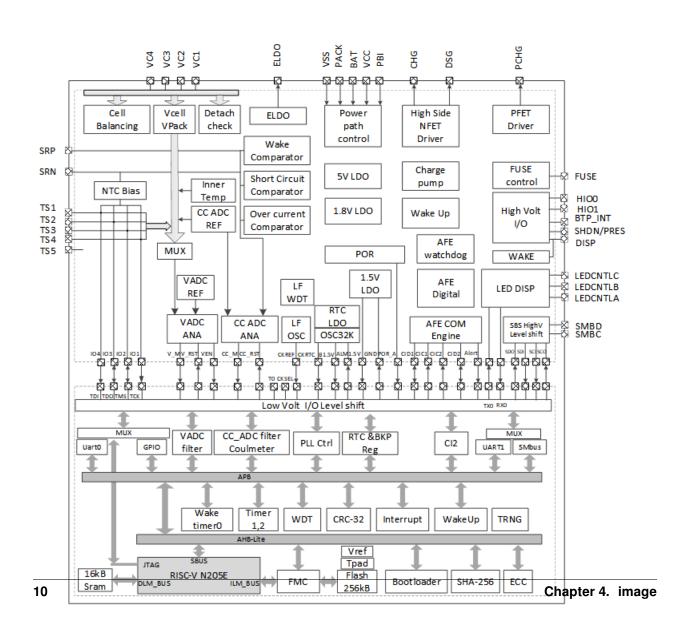
Chapter 2. Power sequencing



Debug mode entry



image



excel

表 5.1: registers summary

	衣 3.1	i. Tegisters summa	пу			
0x40070050 0x01	PHASE_CONFIG					
	8	[7:5]	PH_CFG	RW	3,	000b
	===	F4 O1	CHECK	DIV	b0	=
		[4:0]	CHECK	RW	<i>E</i> ;	1+1+1-
					5'	100b
					b0	= 2+1+1;
						2+1+1, 101b
						=
						2+2
						110b
						=
						3+1
						111b
						=
						4+0
						Oth-
						ers
						are
						re-
						served
						1010b
						=
						The
						writ-
						ing
						com-
						mand
						is
						valid
2					Chapter 5.	data;
=					5ap.o. o.	orc orc

Register1

6.1 trim_vadc

表 6.1: trim_vadc

Bit	23	22	21	20	19	18	17	16
Write	0	0	0	0	0	0	0	0
Read	COM_ERR							
Re- set	0	0	0	0	0	0	0	0

6.2 trim_ptc

表 6.2: trim_ptc

Addr 32'	ess h8000	00000		t addr h0000				ault Valu h0000			Name trim_					
for re	set cor	ntrol														
Bit	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Typ	RSV															
Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Tpy	Rese	rved								R/W	RO	W1C	R/W			
Bit	Fld N	Vame	Rese	t	Desc	ription										
31:0	bit31		0000	0000	1111	111111	11111	11111								
30	bit31				1111	111111	11111	11111								
29	bit31				1111	111111	11111	11111								
28	bit31				1111	111111	11111	11111								
27	bit31				1111	111111	11111	11111								
26	bit31				1111	111111	11111	111								
					2' b	00 - ena	able									
					2' b	01 - dis	able									

Device

7.1 Cyclic Redundant Check generation

An 8 bit CRC is required for each Write and Read SPI and I2C command. Computation of a cyclic redundancy check is derived from the mathematics of polynomial division, modulo two. The CRC polynomial used is $x^8+x^4+x^3+x^2+1$ (identified by 0x1D) with a SEED value of hexadecimal '0xFF' The following is an example of CRC encoding HW implementation:

7.2 spi interface

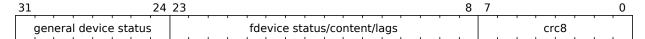
7.2.1 SPI interface overview

MOSI,master out slave in bits

31 30 25	5 24 23	8 7	0
sel register address	r/w control bits	crc8	

-Bit 31: main or fail-safe registers selection -Bit 30 to 25: register address -Bit 24: read/write -Bit 23 to 8: control bits -Bit7 to 0: cyclic redundant check (CRC)

MISO, master in slave out bits



-Bit 31-24: general device status -bits 23 to 8: extended device status, or device internal control register content or device flags -Bit7 to 0: cyclic redundant check (CRC)

The digital SPI pins (CSB, SCLK, MOSI, MISO) are referenced to VDDIO.

7.2.2 SPI CRC calculation and results

7.2.3 Spi interface timing

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NVM-OTP

8.1 待确认

MACRO NAME: DesignWare slp_b_tsmc180bcd50_128x8_cm8s_ab 供电共有 VDD(1V8) VPP(8V18) VRR(3V) VREF(==VDD or external IO) , size 是 8bit

8.1.1 供电电压

两种供电方式,首先确认 IPS controls 是不是集成在 IP 里面,能否分离。如果使用 IPS 供电那只需要提供 VDD(1V8) 和 VDD_IO(5V)

Table 1-1. Configuration Summar	у							
Parameter	Supply	Min ^[1]	Тур	Max ^[1]	Units			
General					100			
Process Node		TSMC 18	80nm BCD50 1	.8/5.0 V	-0,			
Configuration Metal Layers			M4 is thin	(700			
Memory size			1k		7 16			
I/O Bus width (n)			8 bits	70	:10			
Organization S x R x CM x bits		1 arrays x 16 r	ows x 8 Colum	n Mux x 8 bits	S			
		128 words x	8 bits (Single	Cell Mode)	2			
Number of Arrays			1	4. 00.				
Address Bus width			7,0	. 10				
Area	Х	X = 188.81μm x Y = 92.18μm Area = 0.017mm ²						
Retention		10	100	•	Years			
Power Supply	VDD	1.62	1.8	1.98	V			
Current (Standby)	VDD	:.0	0.04	3.5	μA			
Power Supply	VRR	2.7	3.0	3.3	V			
Current (Standby)	VRR	N 11	0.01	0.1	μA			
Program (Single Bit)	he .	, i'C.						
Power Supply	VPP	7.9	8.15	8.4	V			
Current ^[2]	VPP	400	250		μA			
Time	-111	2	100		μs/bit			
Temperature Range	0 11	-40	+25	+125	°C			
Read (Single ended, 8 Bits)	200							
Current (not including standby)	VDD	3.8	4.7	6.1	μΑ/MHz			
Current (not including standby)	VRR	0.9	1.1	1.5	μA/MHz			
Temperature Range	0	-40	+25	+150	°C			
Storage								
Temperature Range		-55	+25	+150	°C			

^{[1]:} Across the conditions described in Corner Conditions on page 18. [2]: One bit at a time programming.

8.1.2 位宽大小

jwq40260 spi/i2c 接口格式使用的是 8+16+8(addr+data+crc), 内部总线也是使用 16 位。如果使用的是 16 位的 数据,那可以直接使用,否则需要数字逻辑转接匹配位宽。

OTP Name	Config	Bitcount ^[1]	X [µm]	Υ [μm]	Area [mm²]
slp_b_tsmc180bcd50_128x8_cm8s	128x8	1024	189	92	0.02
slp_b_tsmc180bcd50_256x8_cm16s	256x8	2048	243	92	0.02
slp_b_tsmc180bcd50_512x8_cm16s	512x8	4096	243	117	0.03
slp_b_tsmc180bcd50_512x8_cm16d 2	512x8	4096	243	142	0.04
slp_b_tsmc180bcd50_512x8_cm16d_r20	512x8	4096	243	161	0.04
slp_b_tsmc180bcd50_256x16_cm16s	256x16	4096	352	92	0.03
slp_b_tsmc180bcd50_1kx8_cm16s	1kx8	8192	243	167	0.04
slp_b_tsmc180bcd50_1kx8_cm16d[2]	1kx8	8192	243	192	0.05
slp_b_tsmc180bcd50_1kx8_cm16d_r20	1kx8	8192	243	211	0.05
slp_b_tsmc180bcd50_512x16_cm16s	512×16	8192	352	117	0.04
slp_b_tsmc180bcd50_512x16_cm16d ^[2]	512×16	8192	352	142	0.05
slp_b_tsmc180bcd50_512x16_cm16d_r20	512×16	8192	352	161	0.06
slp_b_tsmc180bcd50_256x32_cm16s	256x32	8192	571	92	0.05

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Indices and tables

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